



RELIABILITY REPORT
FOR
LM4040Cxx3-x.x+
PLASTIC ENCAPSULATED DEVICES

December 14, 2009

MAXIM INTEGRATED PRODUCTS

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Conclusion

The LM4040Cxx3-x.x+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The LM4040 is a precision two-terminal shunt mode, bandgap voltage reference available in fixed reverse breakdown voltages of 2.048V, 2.500V, 3.000V, 3.3V, 4.096V, and 5.000V. Ideal for space-critical applications, the LM4040 is offered in the subminiature 3-pin SC70 surface-mount package (1.8mm x 1.8mm), 50% smaller than comparable devices in SOT23 surfacemount packages (SOT23 versions are also available). Laser-trimmed resistors ensure precise initial accuracy. With a 100ppm/°C temperature coefficient, the device is offered in four grades of initial accuracy ranging from 0.1% to 1%. The LM4040 has a 60µA to 15mA shunt current capability with low dynamic impedance, ensuring stable reverse breakdown voltage accuracy over a wide range of operating temperatures and currents. The LM4040 does not require an external stabilizing capacitor while ensuring stability with any capacitive load. The LM4040 is guaranteed over the temperature range of -40°C to +125°C. For a 1.225V output version, refer to the LM4041 data sheet.

II. Manufacturing Information

A. Description/Function:	Improved Precision Micropower Shunt Voltage Reference with Multiple Reverse Breakdown Voltages
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Carsem Malaysia, UTL Thailand
F. Date of Initial Production:	July 22, 2000

III. Packaging Information

A. Package Type:	3-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0156
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	250°C/W
K. Single Layer Theta Jc:	130°C/W

IV. Die Information

A. Dimensions:	30 X 31 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 155 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 6.9 \times 10^{-9}$$

$$\lambda = 6.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the B12 Process results in a FIT Rate of 3.13 @ 25C and 54.16 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RF25-x die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

LM4040Cxx3-x.x+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	155	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data